Monitoring Chip Branch Failure in Multichip IGBT Mod

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Citation Report

#	Article	IF	Citations
1	In Situ Diagnosis for IGBT Chip Failure in Multichip IGBT Modules Based on a Newly Defined Characteristic Parameter Low-Sensitive to Operation Conditions. IEEE Transactions on Power Electronics, 2023, 38, 7711-7722.	7.9	1
2	A Junction Temperature Online Monitoring Method for IGBTs Based on Turn-off Delay Time. IEEE Transactions on Industry Applications, 2023, , 1-13.	4.9	0
3	A Health Condition Indicator Localization Method for the Power Devices in Three-Phase Inverter. IEEE Journal of Emerging and Selected Topics in Power Electronics, 2023, 11, 6079-6087.	5.4	0